EPOXY TECHNOLOGY

Epoxy Technology Inc. (简称EPO-TEK®) 成立于1966年， 是一家开发和制造特种环氧树脂的先驱企业， 专为高科技应用提供特种胶粘剂解决方案以满足行业关键性能标准需求。

产品的主要用途包括粘接、封装、密封、涂料、包封、底部填充、层压、光纤包装固封、灌封、焊料替代与散热。我们的环氧树脂产品供应有两种形式：双组分形式（一部分为树脂，一部分为固化剂）及单组分形式（预混合及冷冻灌注器（PMF），以方便使用）。

Epoxy Technology, Inc., founded in 1966, is a pioneer in the development and manufacture of Specialty Epoxy. EPO-TEK® produces a full range of high performance adhesives to meet key performance standards needed in high-tech applications.
The main applications of the products including bonding, packaging, sealing, coating, encapsulation, underfill, lamination, fiber packing sealing, potting, solder replacement and heat sinking. Epoxy products supply the two components (one for the resin, one for hardening agent) and the single component (pre mixed and frozen (PMF), convenient to be used.

导电 & 导热环氧胶粘剂
Electrically & Thermally Conductive Epoxy Adhesives

EPO-TEK®为微电子、光纤、半导体、光电、汽车组件、医疗设备、电子产品组装行业提供全套导电和导热环氧胶粘剂。

EPO-TEK® offers a full range of electrically and thermally conductive epoxy adhesives for the microelectronics, fiber optic, semiconductor, optoelectronics, automotive component, medical device and electronics assembly.

EPOXY TECHNOLOGY	Electrically Conductive / Thermally Conductive (Silver filled)								
	Viscosity cPs,23℃	Pot life	Cure Temperature	Tg ℃	Thixo	Die Shear Strength	VR ohm-cm	ThK w/m°K	Particle Size
H20E	100rpm 2,200-3,200	2.5 days	150℃-1hr	≥80	4.60	≥10kg	≤4 x 10^{-4}	2.50	≤45 μm
H20S	100rpm 1,800-2,800	3 days	150℃-1hr	≥80	5.00	≥5kg	≤5 x 10^{-4}	3.30	≤20 μm
H20E-175	100rpm 2,800-3,800	3.5 days	180℃-1hr	≥85	3.10	≥10kg	≤4 x 10^{-4}	2.00	≤45 μm
H20E-FC	50rpm 1,000-5,000	20 hrs	140℃-10min	≥70	4.60	≥10kg	≤4 x 10^{-4}	2.60	≤45 μm
H20E-PFC	100rpm 3,000-4,000	3 days	150℃-1hr	≥80	6.70	≥5kg	≤4 x 10^{-4}	3.20	≤20 μm
H20E-HC	50rpm 3,500-6,000	2.5 days	150℃-1hr	NA	3.50	≥5kg	≤8x 10^{-5}	10.90	≤45 μm
EK1000	100rpm 1,800-3,600	2 weeks	200℃-30min step { 150℃-1hr 200℃-1hr	≥80	3.60	≥10kg	≤9 x 10^{-5}	12.60 step { 26.30	≤45 μm
EV2118-2	100rpm 1,500-3,000	3 days	150℃-1hr	≥40	4.40	≥5kg	≤5 x 10^{-4}	4.00	≤20 μm
EJ2189-LV	1rpm 25,000-45,000	4 hrs	150℃-1hr 23℃-3days	≥40	3.30	≥10g	≤5 x 10^{-4}	2.50	≤45 μm
EJ2312	1rpm 58,822	90 min	150℃-1hr	≥45	2.60	≥13kg	≤5 x 10^{-4}	-	≤45 μm
E2101	20rpm 15,000-18,000	5 days	150℃-1hr	≥90	3.90	≥5kg	≤5 x 10^{-4}	2.50	≤20 μm
EJ2108	10rpm 11,806	1 hr	80℃-2hrs 23℃-3days	≥42	2.40	≥8g	≤9 x 10^{-5}	4.00	≤20 μm
H22	20rpm 12,000-20,000	16 hrs	150℃-1hr	≥100	2.40	≥5kg	≤5 x 10^{-3}	0.90	≤45 μm
H35-175MP	10rpm 22,000-28,000	28 days	180℃-1hr	≥100	4.00	≥10kg	≤5 x 10^{-4}	1.50	≤20 μm
H37-MP	10rpm 22,800-26,000	28 days	150℃-1hr	≥90	3.60	≥10kg	≤5 x 10^{-4}	1.60	≤20 μm

光学/光纤环氧胶粘剂
Optical/Fiber Optic Epoxy Adhesives

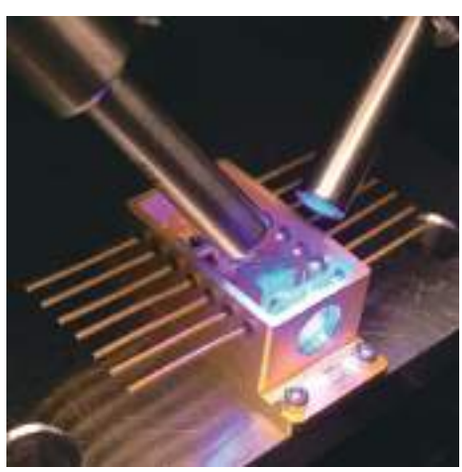
EPO-TEK®光学胶系列适用于光电子器件如电信网络,卫星以及医疗设备和科学仪器中的各种光纤接合及保护涂层应用。 EPO-TEK®353ND是一个众所周知的“光纤连接涂层和光纤插芯的行业标准”。

EPO-TEK® optical line adhesive is used for bonding and protective coatings in various fiber optic applications in optoelectronics devices such as telecommunication network, satellites as well as medical devices and scientific instruments. EPO-TEK® 353ND is a well know "standard in the industry used in fiber connections for coating over stripped fibers or for ferrule potting.

EPOXY TECHNOLOGY	Fiber Optic/Optical								
	Viscosity cPs,23℃	Pot life	Cure Temperature	Tg ℃	CTE(x 10-6 in/in℃) Before Tg/After Tg	Spectral Transmission		Index of Refraction*	Die shear Strength
301	100rpm 100-200	1-2 hrs	65℃-2hrs 23℃-24hrs	≥65	39/98	≥99% ≥97%	382-980 nm 980-1,640 nm	1.519	≥10kg
301-2	100rpm 225-425	8 hrs	80℃-3hrs 23℃-2days	≥80	61/180	≥99% ≥98%	400-1,200 nm 1,200-1,600 nm	1.5318	≥15kg
301-2FL	100rpm 100-200	10 hrs	80℃-3hrs 23℃-3days	≥45	56/211	≥97% ≥99%	1,000-1,600 nm 400-1,000 nm	1.5102	≥10kg
323LP	50rpm 3,500-5,000	24 hrs	150℃-1hr	≥100	51/185	≥94% ≥90%	820-1,620 nm 640-800 nm	1.5704	≥20kg
310M	100rpm 450-850	2.5 hrs	65℃-2hrs 23℃-24hrs	≤30	78/222	≥97% ≥90%	400-1,300 nm 1,400-2,200 nm	1.4969	≥2kg
330	100rpm 350-550	6 hrs	150℃-1hr	≥90	65/162	≥88% ≥97%	600 nm 700-1,600 nm	1.5345	≥10kg
353ND	50rpm 3,000-5,000	≤3 hrs	150℃-1hr	≥90	54/206	≥98% ≥95%	800-1,000 nm 1,100-1,600 nm	1.5694	≥15kg
354	50rpm 4,000-6,000	3 days	150℃-1hr	≥95	96/175	≥99% ≥96%	800 nm 600 nm	1.5734	≥10kg
377	100rpm 150-300	24 hrs	150℃-1hr	≥95	57/210	≥90% >98%	600-1,000nm 1,000-1,600nm	1.5195	≥10kg
353ND-T	20rpm 9,000-15,000	3 hrs	150℃-1hr	≥90	43/231	N/A		N/A	≥15kg
383ND	50rpm 3,500-6,000	8 hrs	150℃-1hr	≥100	34/129	≥90%	520-1,660nm	1.5715	≥20kg
OD2002	5rpm 24,000-42,000	4 hrs	150℃-1hr	≥140	45/187	>98%	800-1,640nm	1.5728	≥10kg
OE145-5	100rpm 1,163	2 hrs	65℃-3hrs	≥59	N/A	>95%	560-2,060nm	1.5424	≥24kg
OE188-3	1rpm 200,000-400,000	2 hrs	150℃-1hr	≥90	23/97	62%	1,550nm	1.5613	≥15kg
302-3M-R	100rpm 592	2 hrs	80℃-1hr	≥61	N/A	>98%	460-1,620nm	1.5442	≥24kg

*@589nm

UV固化胶粘剂
UV Curing Adhesives



EPO-TEK®紫外光固化环氧树脂胶粘剂有着优异的粘接性和高可靠性，低收缩，无表面氧抑制反应，能够“阴影”固化及热固化或后热固化以增强粘接强度。

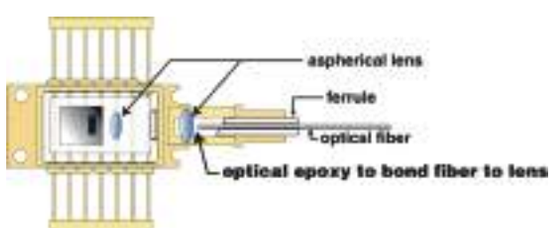
The advantage of EPO-TEK® epoxy based UV adhesives is excellent adhesion and reliability, low shrinkage, not subject to oxygen inhibition, capable of “Dark” curing and heat/thermal post-cure to enhance the bonding strength.

UV Curing							
	Viscosity cPs,23℃	Tg ℃	Die Shear Strength (UV Only)	Spectral Transmission	Outgassing @200℃	Index of Refraction*	Storage Modulus
OG116	2.5rpm 80,000-105,000	≥135	≥10kg	≥98% 560-1,660nm	0.19%	1.5892	215,745psi
OG116-31	10rpm 20,000-30,000	≥115	≥10kg	≥96% 660-1,640nm ≥92% 500nm	0.30%	1.5842	263,581 psi
OG142-112	100rpm 1,200-1,700	≥90	≥20kg	≥97% 500-1,660nm	0.27%	1.5560	592,522psi
OG159-2	2.5rpm 100,000-140,000	≥30	≥5kg	≥98% 580-2,000nm	0.13%	1.5715	341,084psi
OG142	20rpm 9,000-15,000	≥95	≥4kg	≥97% 660-1,640nm ≥92% 440-620nm	0.20%	1.5809	558,079psi
OG154-1	5rpm 26,000-34,000	128	≥10kg	≥97% 500-1,660nm	0.17%	1.5692	265,655psi
OG198-54	100rpm 200-450	131	≥10kg	≥97% 460-1,660nm	0.24%	1.5256	449,431 psi
OG198-55	100rpm 1,200-2,000	≥120	≥20kg	≥97% 560-1,680nm	0.23%	1.5196	489,872psi
OG603	100rpm 150-250	≥70	≥3kg	≥98% 420-1,600nm	0.79%	1.5037	250,734psi
OG142-87	100rpm 250-600	≥100	≥25kg	≥97% 580-1,660nm	0.32%	1.5058	520,650 psi
UD1355	100rpm 447	≥36	≥19.6kg	≥99% 360-780nm ≥96% 800-2,200nm	2.85%	1.4925	N/A
OG133-7	100rpm 150-450	≤10	≥2.5kg	≥95% 600nm ≥96% 800-1,600nm	1.55%	1.5060	<1,000 psi
OG133-8	100rpm 1,000-1,500	≤10	≥3.2kg	≥90% 580-800nm ≥95% 820-1,660nm	2.37%	1.5244	<1,000 psi

*@589nm

紫外光混合系统胶粘剂

EPO-TEK®UV Hybrid Adhesives



Epoxy Technology 开发了全新的产品线，主要以环氧树脂为化学基础的UV混合系统胶粘剂（UV Hybrid Adhesives）。这个全新的产品配方技术可以通过利用UV及热固化的掌控，有效的改良工艺上的操作流程。可以在短短几秒钟以内完成预固化， 接着再后热固化；从而在工艺上达到了速度与强度的结合。

Epoxy Technology has developed a line of unique epoxy-based, UV Hybrid chemistry adhesives. These new, “state-of-the-art” formulations allow for improved handling and process control by utilizing both UV and thermal curing. Tacking can be done in seconds, followed up by heat; giving both speed and strength to the process.

UV Hybrid Adhesives								
	Viscosity	Pot Life	Tg ℃	Degradation Temp(℃)	Weight loss	Die shear(kg)	Spectral Transmission	Index of Refraction*
HYB-353ND-LV	100rpm 800-2,000	<20 hrs	≥80	400	0.08%	≥15	≥95% 1,100-1,600nm ≥98% 800-1,000nm	1.5215
HYB-353ND	10rpm 3,000-7,000	<2 hrs	≥100	400	0.06%	≥20	≥95% 1,100-1,600nm ≥98% 800-1,000nm	1.5259
HYB-353ND-HV	10rpm 9,000-20,000	2 hrs	≥100	388	0.03%	≥25	≥95% 1,100-1,600nm ≥98% 800-1,000nm	1.5545
HYB-353ND-TX2	10rpm 20,000-32,000	<2 days	≥90	410	0.05%	≥15	≥95% 1,100-1,600nm ≥98% 800-1,000nm	+N/M
HYB-353ND-TX3	10rpm 25,000-41,000	<3 days	≥80	399	0.19%	≥15	≥95% 1,100-1,600nm ≥98% 800-1,000nm	+N/M
HYB-297-RT	100rpm 323	4 hrs	63	350	0.25%	13.4	≥99% 400-1,600nm	1.5182
HYB-297-RT-HV	100rpm 613	<3 hrs	51	371	0.08%	28.5	≥95% 580-1,660nm	1.5181

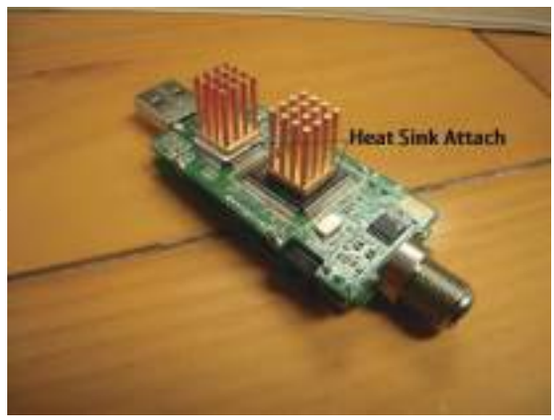
*Uncured at 589nm　　+Not measured

- 提高整体产线工艺流程，易操作
- 更低的应力和收缩率
- 增加昂贵的耦合设备上的产量
- 几秒钟内完成表干预固化
- 85℃/85%RH性能可媲美353ND

- Overall process improvement, easier handling
- Lower stress and less shrinkage
- Increased thru-put on expensive alignment machines
- Tack free in seconds
- 85°C/85%RH resistance, comparable to 353ND

导热/电绝缘环氧胶粘剂

Thermally Conductive / Electrically Insulating Epoxy Adhesive



EPO-TEK® 导热环氧树脂能有效地散热, 从而提高介电强度及保护电路免受恶劣环境破坏。我们的环氧树脂属性范围从坚硬(提供坚固耐用的、抗热电路保护)到柔软(适合有重大热膨胀系数差异的基板)。

EPO-TEK® thermally conductive epoxies are effectively removing heat, providing increased dielectric strength and protecting circuit from hostile environments. The epoxy properties are range from rigid (providing robust, thermally enhance circuit protection) to flexible (ideal for substrates with significant CTE mismatches).

Thermally conductive/Insulating (Non silver filled)									
EPOXY TECHNOLOGY	Viscosity cPs,23℃	Pot life	Cure Temperature	Tg ℃	Thixo	Die Shear Strength	VR ohm-cm	ThK w/m^{0}K	Particle Size
H70E	50rpm 4,000-7,000	56 hrs	150℃-1hr	≥80	1.20	≥10kg	≥1 x 10^{13}	0.90	≤50 μm
H70E-2	20rpm 9,000-15,000	2 days	150℃-1hr	≥80	1.70	≥5kg	≥8 x 10^{12}	1.00	≤50 μm
H70S	100rpm 1,300-1,800	3 days	150℃-1hr	≥50	1.40	≥10kg	≥7 x 10^{13}	0.40	≤20 μm
H74	5rpm 45,000-65,000	2 hrs	150℃-1hr	≥100	2.14	≥15kg	≥4 x 10^{12}	1.30	≤50 μm
H77	20rpm 6,000-12,000	6 hrs	150℃-1hr	≥80	1.40	≥5kg	≥1 x 10^{13}	0.70	≤50 μm
930-4	20rpm 12,000-17,000	1 day	150℃-1hr	≥90	2.40	≥15kg	≥2x 10^{13}	1.70	≤20 μm
H65-175MP	2.5rpm 80,000-120,000	28 days	180℃-1hr	≥110	1.87	≥20kg	≥1.2 x 10^{14}	0.80	≤20 μm
H67-MP	1rpm 300,000-400,000	28 days	150℃-1hr	≥90	N/A	≥20kg	≥6 x 10^{13}	0.50	≤20 μm
T7109	20rpm 14,000-20,000	4 hrs	150℃-1hr	≥45	1.79	≥15kg	≥8 x 10^{12}	1.50	≤20 μm
T7109-19	5rpm 40,000-70,000	2 hrs	80℃-2hrs	≥40	2.70	≥5kg	≥5 x 10^{12}	1.30	≤20 μm
T905BN-3	50rpm 2,000-7,000	3 hrs	80℃-2hrs	≥40	1.50	≥10kg	≥3 x 10^{11}	2.0	≤300 μm
TV2001	20rpm 10,000-20,000	2 days	160℃-5min	≥15	2.00	≥15kg	≥8x 10^{12}	0.40	≤20 μm
TJ2139-LH	10rpm 22,000-34,000	2.5 days	150℃-1hr	≥100	1.80	≥20kg	≥9.57 x 10^{13}	0.50	≤20 μm
T7110	100rpm 1,400-2,200	3.5 hrs	80℃-2hrs 23℃-3days	≥40	2.20	≥10kg	≥2 x 10^{13}	1.00	≤50 μm
TZ101	10rpm 24,000-30,000	28 days	150℃-1hr	≥40	3.70	≥10kg	≥2 x 10^{13}	0.90	≤20 μm
TD1001	5rpm 10,000-22,000	28 Days	125℃-1hr	≥40	4.10	≥15kg	≥2 x 10^{13}	0.8	≤20 μm

为何要选用EPO-TEK预混型胶粘剂?

- 提高可靠性和稳定性 -混合比例精确
- 增加成本效益-节约操作时间，提高生产率
- 更少接触到化学危害物和低损耗，降低环境损害
- 易操作-方便，无需测量，无需混合，解冻后即可使用，摆脱混合风险。

注: 页面的技术信息和数据仅作为参考, 不作为说明书使用。

Why Use EPO-TEK® Packaged Adhesives?

- Increased Reliability/Consistency/Uniformity—Precise Mix Ratio, Lot to Lot
- Cost Effective—Time Saving in Preparation of Material, Increased Productivity
- Less Exposure to Chemical Hazards, Reduced Waste, and Packaging Centers of Excellence Lower Environmental Impact
- Ease of Use—Convenient, No Measuring, No Mixing, Ready to Use, Stress Free

Note: The technical information and data on these pages should be considered representative or typical only and should not be used for specification purposes.

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